

Mohd Foad

List of Publications by Year in descending order

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Version: 2024-02-01

16
papers

190
citations

1163117

8
h-index

1372567

10
g-index

16
all docs

16
docs citations

16
times ranked

115
citing authors

| # | ARTICLE | IF | CITATIONS |
|----|--|-----|-----------|
| 1 | Thermomigration induced degradation in solder alloys. Journal of Applied Physics, 2008, 103, . | 2.5 | 38 |
| 2 | Influence of Thermomigration on Lead-Free Solder Joint Mechanical Properties. Journal of Electronic Packaging, Transactions of the ASME, 2009, 131, . | 1.8 | 33 |
| 3 | Thermomigration Versus Electromigration in Microelectronics Solder Joints. IEEE Transactions on Advanced Packaging, 2009, 32, 627-635. | 1.6 | 30 |
| 4 | Simulating Damage Mechanics of Electromigration and Thermomigration. Simulation, 2008, 84, 391-401. | 1.8 | 17 |
| 5 | Damage Mechanics of Low Temperature Electromigration and Thermomigration. IEEE Transactions on Advanced Packaging, 2009, 32, 478-485. | 1.6 | 17 |
| 6 | Low temperature electromigration and thermomigration in lead-free solder joints. Mechanics of Materials, 2009, 41, 1223-1241. | 3.2 | 17 |
| 7 | Thermomigration in lead-free solder joints. International Journal of Materials and Structural Integrity, 2008, 2, 11. | 0.1 | 16 |
| 8 | Methodology for reliability assessment of steel wire ropes under fretting fatigue conditions. Journal of Mechanical Engineering and Sciences, 2017, 14, 2488-2502. | 0.6 | 14 |
| 9 | Fractal Dimensions of a Propagating Fatigue Crack in Metallic Materials. Journal of Failure Analysis and Prevention, 2021, 21, 1644-1651. | 0.9 | 5 |
| 10 | Rate-dependent responses of electroless plated and sputtered copper layer during nanoindentation loading. , 2016, , . | | 1 |
| 11 | Predictive maintenance model for centrifugal pumps under improper maintenance conditions. AIP Conference Proceedings, 2020, , . | 0.4 | 1 |
| 12 | Experimental Study of Thermomigration in Lead-Free Nanoelectronics Solder Joints. , 2006, , . | | 1 |
| 13 | Low temperature electromigration and thermomigration in lead-free solder joints. , 2008, , . | | 0 |
| 14 | A review of computational damage mechanics of mass transport in solder joint. , 2014, , . | | 0 |
| 15 | Mass Migration Damaged Based Model and the Behaviour of Electromigration and Thermomigration in Interconnect. , 2018, , . | | 0 |
| 16 | Thermomigration Induced Strain Field Simulation for Microelectronic Lead Free Solder Joints. , 2006, , . | | 0 |